

# WP934ZH/GD

T-1 (3mm) Single-Level Circuit Board Indicator



 The Green source color devices are made with Gallium Phosphide Green Light Emitting Diode

## **FEATURES**

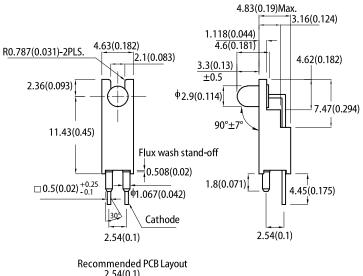
- · Pre-trimmed leads for pc board mounting
- Black case enhances contrast ratio
- Wide viewing angle
- · High reliability life measured in years
- Housing UL rating: 94V-0
- Housing material: Type 66 nylon
- RoHS compliant

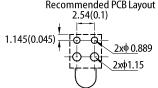
### **APPLICATIONS**

- Status indicator
- Illuminator
- Signage applications
- · Decorative and entertainment lighting
- · Commercial and residential architectural lighting



# PACKAGE DIMENSIONS





Notes.

1. All dimensions are in millimeters (inches)

- An unimerisions are in minimizers (inclusion).
  Tolerance is ±0.25(0.01") unless otherwise noted.
  Lead spacing is measured where the leads emerge from the package.
  The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

### SELECTION GUIDE

Part Number	Emitting Color	Lens Type	lv (mcd) @ 10mA <sup>[2]</sup>				Viewing Angle <sup>[1]</sup>
Fait Number	(Material)	Lens Type	Min.	Тур.	201/2		
WP934ZH/GD	Green (GaP)	Green Diffused	10	25	50°		

Notes

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
  Luminous intensity / luminous flux: +/-15%.
- Luminous intensity value is traceable to CIE127-2007 standards.

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### ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Parameter	Sympol	Emitting Color	Value		Unit
Farameter	Symbol	Emitting Color	Typ. Max.		
Wavelength at Peak Emission $I_F$ = 10mA	$\lambda_{peak}$	Green	565	-	nm
Dominant Wavelength I <sub>F</sub> = 10mA	$\lambda_{dom}$ <sup>[1]</sup>	Green	568	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX $I_F$ = 10mA	Δλ	Green	30	-	nm
Capacitance	С	Green	15	-	pF
Forward Voltage I <sub>F</sub> = 10mA	V <sub>F</sub> <sup>[2]</sup>	Green	2	2.4	V
Reverse Current ( $V_R = 5V$ )	I <sub>R</sub>	Green	-	10	μA
Temperature Coefficient of $\lambda_{\text{peak}}$ $I_F$ = 10mA, -10°C $\leq T \leq 85^\circ C$	TC <sub>λpeak</sub>	Green	0.1	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 10mA, -10°C $\leq T \leq 85^\circ C$	TC <sub>λdom</sub>	Green	0.06	-	nm/°C
Temperature Coefficient of V <sub>F</sub> $I_F$ = 10mA, -10°C $\leq$ T $\leq$ 85°C	TCv	Green	-2	-	mV/°C

Notes:

The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd : ±1nm.)
 Forward voltage: ±0.1V.
 Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

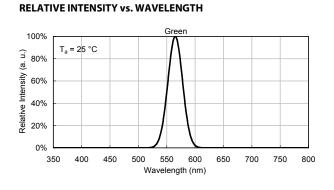
# ABSOLUTE MAXIMUM RATINGS at $T_A=25^{\circ}C$

Parameter	Symbol	Value	Unit	
Power Dissipation	PD	62.5	mW	
Reverse Voltage	V <sub>R</sub>	5	V	
Junction Temperature	Tj	110	°C	
Operating Temperature	T <sub>op</sub>	-40 to +85	°C	
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C	
DC Forward Current	١ <sub>F</sub>	25	mA	
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	140	mA	
Electrostatic Discharge Threshold (HBM)	-	8000	V	
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	680	°C/W	
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	460	°C/W	
Lead Solder Temperature <sup>[3]</sup>		260°C For 3 Seconds		
Lead Solder Temperature [4]		260°C For 5 Seconds		

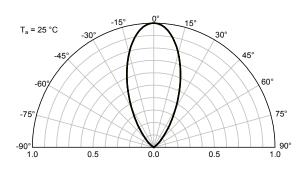
Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. R<sub>In JA</sub>, R<sub>E</sub> sufts from mounting on PC board FR4 (pad size ≥ 16 mm<sup>2</sup> per pad). 3. 2mm below package base. 4. 5mm below package base. 5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

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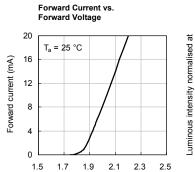
# **TECHNICAL DATA**

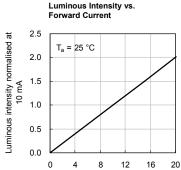


#### SPATIAL DISTRIBUTION



GREEN

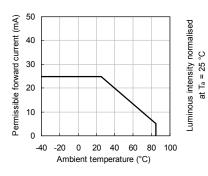


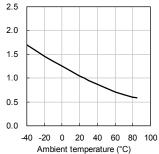


Forward current (mA)

Forward Current Derating Curve

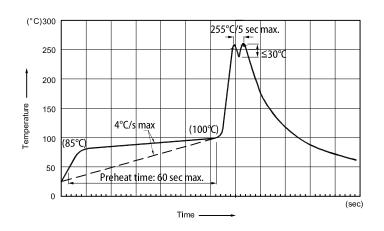
Luminous Intensity vs. Ambient Temperature





# **RECOMMENDED WAVE SOLDERING PROFILE**

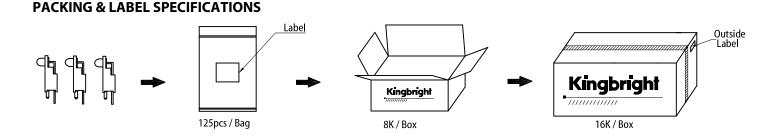
Forward voltage (V)



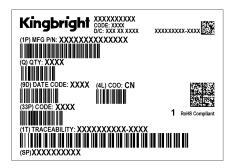
#### Notes:

 Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).

- Do not apply stress to the epoxy resin while the temperature is above 85°C.
  Fixtures should not incur stress on the component when mounting and during soldering process.
- 5. SAC 305 solder alloy is recommended.
  6. No more than one wave soldering pass



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# PRECAUTIONS

#### **Storage Conditions**

- 1. Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- 2. LEDs should be stored with temperature  $\leq 30^{\circ}$ C and relative humidity  $< 60^{\circ}$ .
- 3. Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at 85 ~ 100°C.

#### **LED Mounting Method**

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement.

Lead-forming may be required to insure

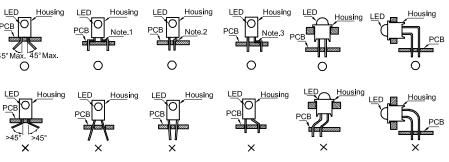
the lead pitch matches the hole pitch.

Refer to the figure below for proper lead forming procedures.

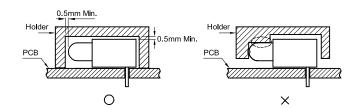
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

#### Lead Forming Procedures

- 1. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.
- 2. The tip of the soldering iron should never touch the lens epoxy.
- 3. Through-hole LEDs are incompatible with reflow soldering.
- 4. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.



○ " Correct mounting method " x " Incorrect mounting method



#### PRECAUTIONARY NOTES

- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications. 2
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